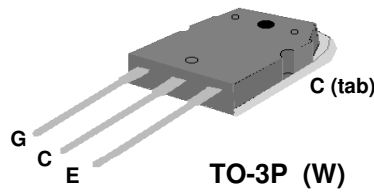


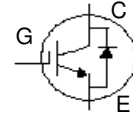


N-Channel Insulated Gate Bipolar Power Transistor

High Speed Switching
Low Saturation Voltage
Typical $V_{CE(sat)} = 2.6V$ at $I_C=33A$
Built-in Fast Recovery Diode
RoHS-compliant, halogen-free



V_{CES}	600V
I_C	45A



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GE}	Gate-Emitter Voltage	± 30	V
I_C at $T_C=25^\circ C$	Collector Current	75	A
I_C at $T_C=100^\circ C$	Collector Current	45	A
I_{CM}	Pulsed Collector Current	150	A
I_F at $T_C=25^\circ C$	Diode Forward Current	40	A
I_F at $T_C=100^\circ C$	Diode Forward Current	15	A
P_D at $T_C=25^\circ C$	Maximum Power Dissipation	300	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	150	$^\circ C$
T_L	Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds .	300	$^\circ C$

Notes:

1. Pulse width limited by maximum junction temperature.

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Thermal Resistance Junction-Case	0.42	$^\circ C/W$
Rthj-c(Diode)	Thermal Resistance Junction-Case	1.5	$^\circ C/W$
Rthj-a	Thermal Resistance Junction-Ambient	40	$^\circ C/W$

Electrical Specifications at $T_J=25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I_{GES}	Gate-to-Emitter Leakage Current	$V_{GE}=\pm 30V, V_{CE}=0V$	-	-	± 100	nA
I_{CES}	Collector-Emitter Leakage Current	$V_{CE}=600V, V_{GE}=0V$	-	-	500	μA
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=33A$	-	2.6	3	V
		$V_{GE}=15V, I_C=50A$	-	3.1	3.5	V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE}=V_{GE}, I_C=250\mu A$	2	-	6	V
Q_g	Total Gate Charge	$I_C=33A$	-	55	100	nC
Q_{ge}	Gate-Emitter Charge	$V_{CE}=400V$	-	12	-	nC
Q_{gc}	Gate-Collector Charge	$V_{GE}=15V$	-	27	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CE}=390V,$ $I_C=33A,$	-	27	-	ns
t_r	Rise Time	$V_{GE}=15V,$ $R_G=5\Omega,$	-	22	-	ns
$t_{d(off)}$	Turn-off Delay Time	Inductive Load	-	110	-	ns
t_f	Fall Time		-	100	260	ns
E_{on}	Turn-On Switching Loss		-	0.7	-	mJ
E_{off}	Turn-Off Switching Loss	-	1.2	-	mJ	
C_{ies}	Input Capacitance	$V_{GE}=0V$	-	1250	2000	pF
C_{oes}	Output Capacitance	$V_{CE}=30V$	-	235	-	pF
C_{res}	Reverse Transfer Capacitance	$f=1.0MHz$	-	7	-	pF

V_F	FRD Forward Voltage	$I_F=15A$	-	1.3	1.7	V
t_{rr}	FRD Reverse Recovery Time	$I_F=15A$	-	65	-	ns
Q_{rr}	FRD Reverse Recovery Charge	$di/dt = 200 A/\mu s$	-	230	-	nC

Ordering Information

AP50G60SW-HF-3TB : in RoHS-compliant halogen-free TO-3P, shipped in tubes (1440 pcs/carton)

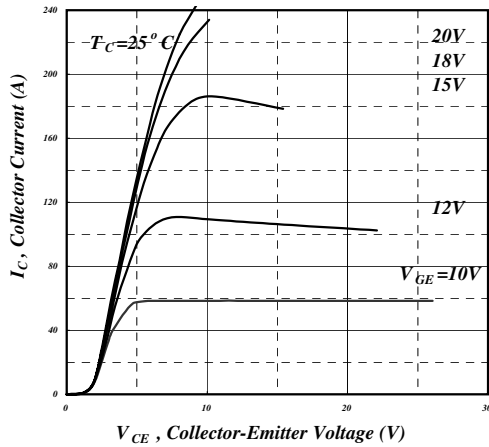


Fig 1. Typical Output Characteristics

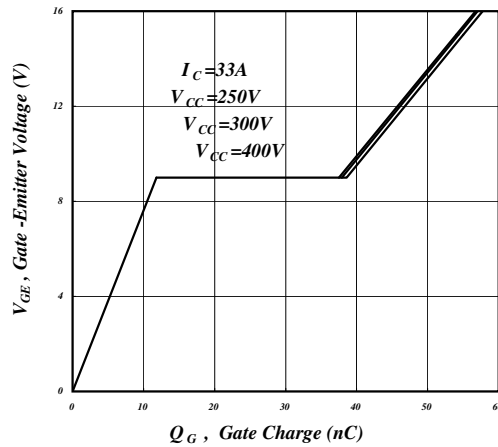


Fig 2. Gate Charge Characteristics

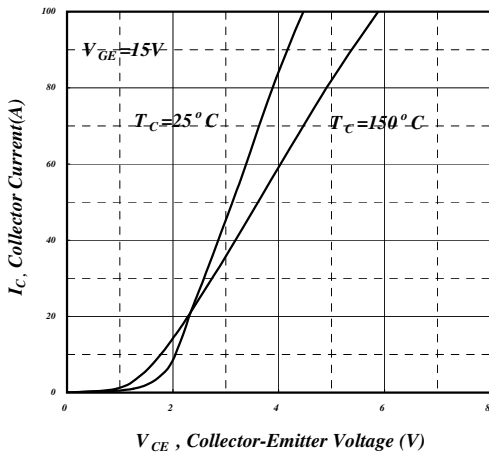


Fig 3. Typical Saturation Voltage Characteristics

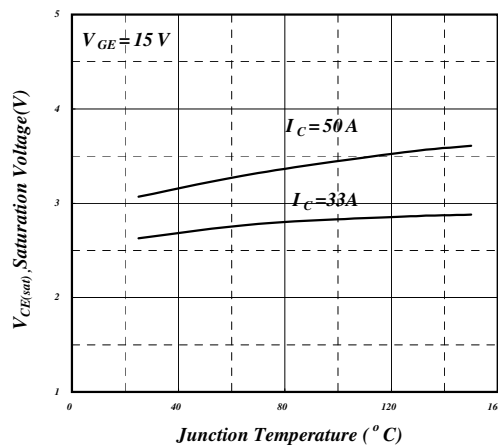


Fig 4. Typical Collector- Emitter Voltage vs. Junction Temperature

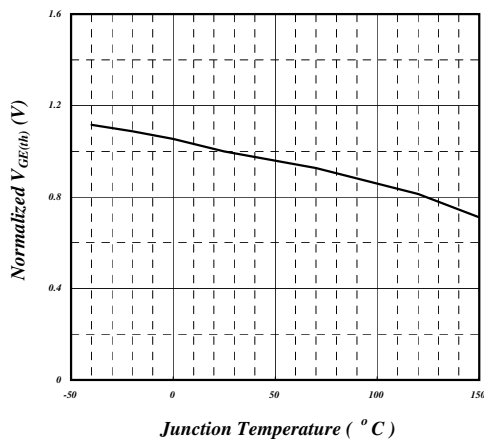


Fig 5. Gate Threshold Voltage vs. Junction Temperature

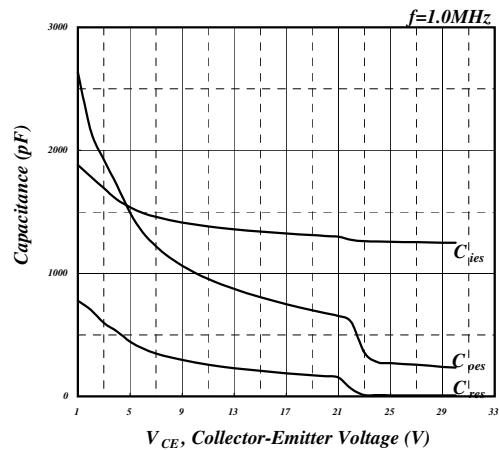


Fig 6. Typical Capacitance Characteristics

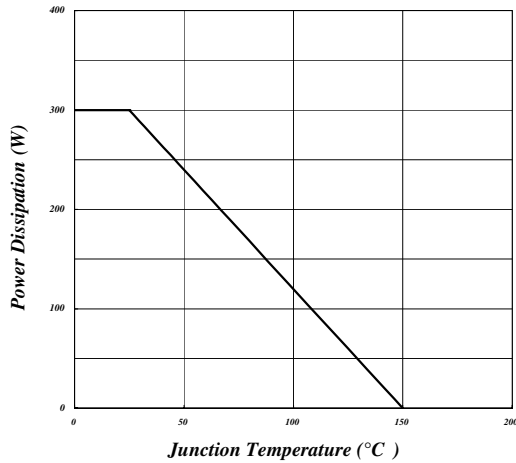


Fig 7. Power Dissipation vs. Junction Temperature

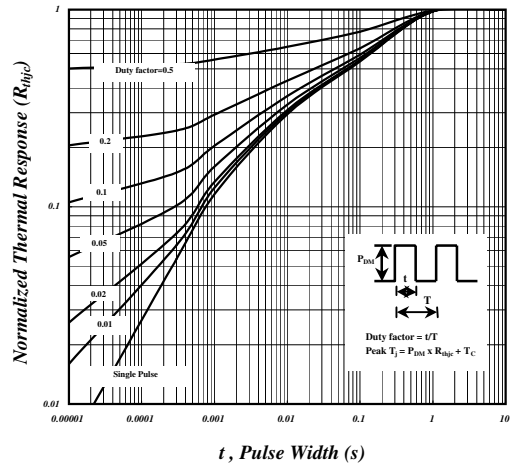


Fig 8. Effective Transient Thermal Impedance

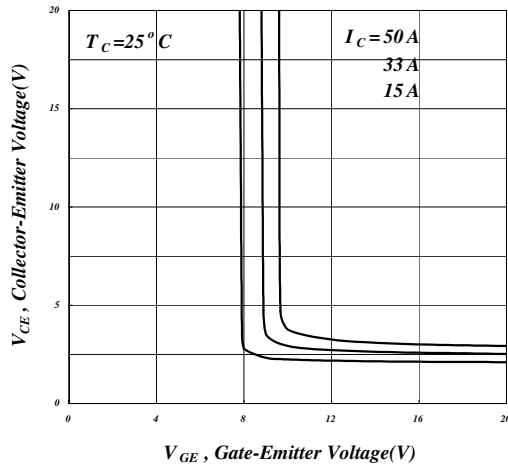


Fig 9. Saturation Voltage vs. V_{GE}

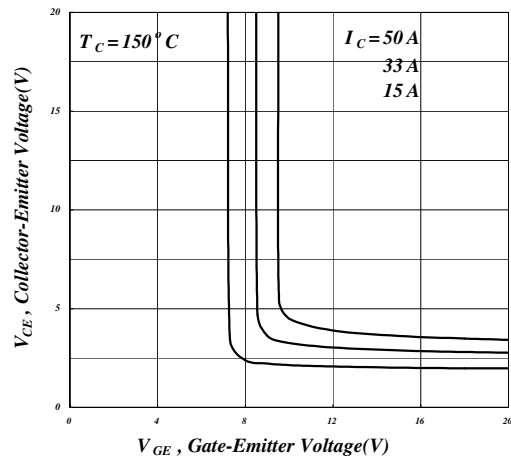


Fig 10. Saturation Voltage vs. V_{GE}

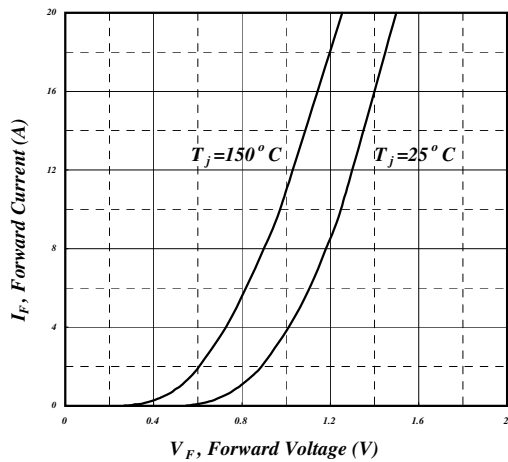


Fig 11. Forward Characteristic of Diode

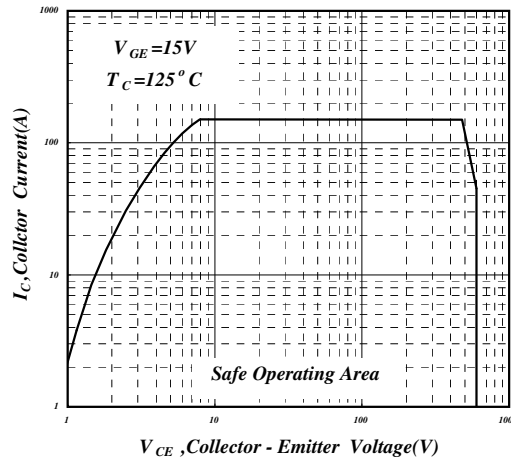
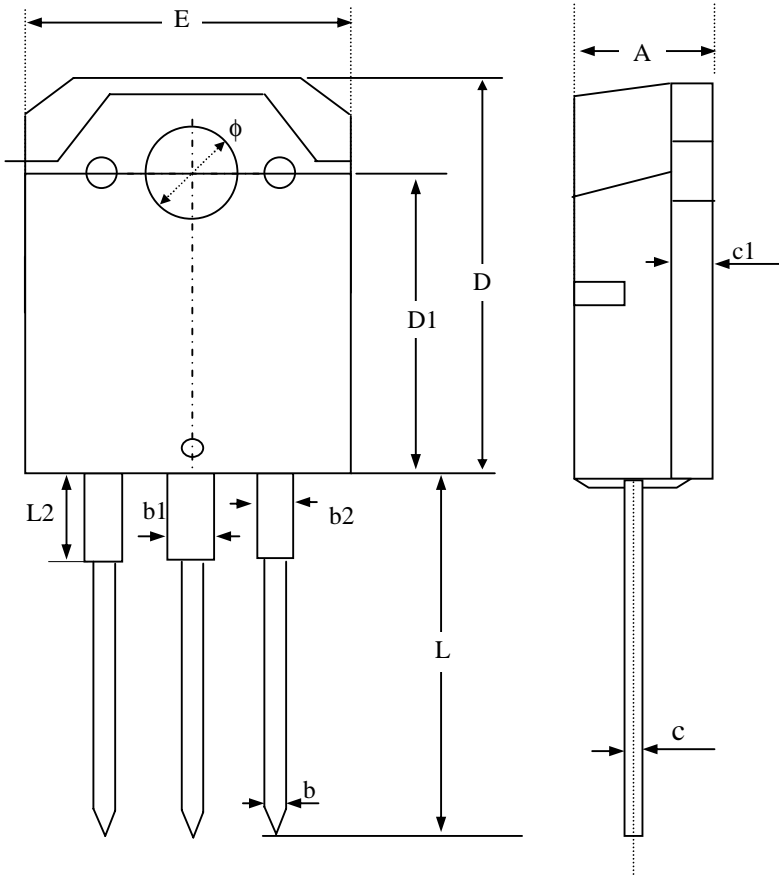


Fig 12. Turn-off SOA

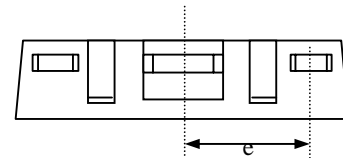


Package Dimensions: TO-3P



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	4.50	4.80	5.10
b	0.80	1.00	1.30
b1	1.80	2.50	3.20
b2	1.30	--	2.30
c	0.40	0.60	0.90
c1	1.40	--	2.20
D	19.70	20.00	20.30
D1	14.70	15.00	15.30
E	15.30	--	16.10
e	4.45	5.45	6.45
L	17.50	--	20.50
L2	1.00	--	3.70
ϕ	3.00	3.20	3.40

1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.



Marking Information:

